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Henning Schröder
Ray T. Chen
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Contents

vii *Authors*
ix *Conference Committee*

SESSION 1 ELECTRICAL-OPTICAL PCB TECHNOLOGIES

- 10924 02 **Single-mode polymer waveguides and devices for high-speed on-board optical interconnect application (Invited Paper)** [10924-1]
- 10924 03 **Erbium-doped polymer waveguide amplifiers for PCB-integrated optical links** [10924-3]
- 10924 04 **Mode-mixing in multimode polymer waveguides for on-board optical interconnects** [10924-4]
- 10924 05 **Large-size directly inscribed polymer waveguide device for card-to-card optical interconnects application** [10924-5]

SESSION 2 OPTICAL INTERCONNECT DEVICES AND MODULATORS

- 10924 07 **Ultra-low power consumption silicon photonic link design analysis in the AIM PDK** [10924-7]

SESSION 3 HYBRID INTEGRATED OPTICAL LINK MODULES

- 10924 0D **Through-substrate coupling elements for silicon-photonics-based short-reach optical interconnects (Invited Paper)** [10924-13]
- 10924 0E **A new generation of high-speed electro-optical transceivers and flexible bandwidth wavelength selective switches for coherent DCI: the QAMEleon project approach (Invited Paper)** [10924-14]

SESSION 4 OPTICAL INTERCONNECT SYSTEMS I

- 10924 0F **Fast optical switching technologies for inter/intra data center networks (Invited Paper)** [10924-15]
- 10924 0H **Automated logic synthesis for electro-optic computing in integrated photonics** [10924-17]
- 10924 0I **Modular test system for high-speed silicon photonics transceivers** [10924-18]

SESSION 5 NOVEL OPTICAL WAVEGUIDE AND INTERCONNECT TECHNOLOGIES

- 10924 0N **SiN-assisted polymer-to-SiPh adiabatic coupler optimization** [10924-22]
- 10924 0O **Evaluation of the coupling performance and long-term stability of aerosol jet printed and photolithographic manufactured waveguides for asymmetric optical bus couplers** [10924-23]

SESSION 6 NANOPHOTONICS FOR OPTICAL INTERCONNECTS

- 10924 0R **Transfer of information using surface-plasmon-polariton waves** [10924-26]
- 10924 0T **Dielectric metamaterial waveguide for optical interconnect and sensing (Invited Paper)** [10924-28]

SESSION 7 FIBER OPTICS AND MICRO-OPTICS INTEGRATION

- 10924 0U **3D laser direct writing for advanced photonic integration (Invited Paper)** [10924-29]
- 10924 0W **Fiber-coupled photonic interconnects based on stacked glass block connectors** [10924-31]
- 10924 0X **Solder-reflowable single-mode fiber array photonics assembly in high-throughput manufacturing facilities (Invited Paper)** [10924-32]

SESSION 8 PICS FOR OPTICAL INTERCONNECTS

- 10924 0Z **BaTiO₃-based modulators for integrated optical interconnects (Invited Paper)** [10924-34]
- 10924 10 **MOICANA: monolithic cointegration of QD-based InP on SiN as a versatile platform for the demonstration of high-performance and low-cost PIC transmitters (Invited Paper)** [10924-35]
- 10924 11 **High-speed energy-efficient InP photonic integrated circuit transceivers (Invited Paper)** [10924-36]
- 10924 12 **Generation and recombination of free carriers in silicon nano-waveguides (Invited Paper)** [10924-37]

SESSION 9 HYBRID DEVICE INTEGRATION APPROACHES FOR SILICON PHOTONIC CHIPS

- 10924 14 **Unidirectional data center interconnects enabled by the use of broken-symmetry gap plasmon resonators (BS-GPR)** [10924-39]

- 10924 15 **Problems, challenges, and a critical survey on automated silicon photonics packaging and optical interconnection (Invited Paper)** [10924-40]
- 10924 16 **Backside optical I/O module for Si photonics integrated with electrical ICs using fan-out wafer-level packaging technology (Invited Paper)** [10924-41]
- 10924 17 **Polarization-insensitive glass-to-silicon photonics coupler** [10924-42]

POSTER SESSION

- 10924 1A **Wireless link evaluation of a dielectric resonator nanoantenna** [10924-45]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abel, Stefan, 0Z
Agrahari, Rajan, 0R
Aldaya, Ivan, 12
Alexoudi, T., 0E
Ambrosius, H. P. M. M., 11
Apostolopoulos, D., 0N, 17
Avramopoulos, H., 0E, 0N, 17
Bamiedakis, Nikos, 03, 04
Barwicz, Tymon, 0X
Bergman, Keren, 07
Bock, Karlheinz, 0O
Boyer, Nicolas, 0X
Brauda, Daniel, 0W
Caillaud, C., 10
Calo, C., 10
Chang, Ching-Wen, 0T
Chatzitheocharis, D., 10
Chen, Ray T., 0H, 0T
Chu, D., 04
Chung, Chi-Jui, 0T
Cyr, Elaine, 0X
Dai, Liang Yuan, 07
Dainese, Paulo, 12
Dereux, Alain, 14
Dhar, Shounak, 0H
Dris, S., 0E
Eisenstein, G., 10
Eltes, Felix, 0Z
Feng, Chenghao, 0H
Fompeyrine, Jean, 0Z
Fortier, Paul, 0X
Fraguito, Hugo L., 12
Franke, Jörg, 0O
Furuyama, Hideto, 16
Gabrielli, Lucas H., 12
Giardina, P. G., 0E
Gil-Molina, Andres, 12
Glick, Madeleine, 07
Goobar, E., 0E
Hashimoto, Toshikazu, 0F
He, Zuyuan, 02, 05
Hernandez-Figueroa, Hugo E., 1A
Hersent, R., 0E
Herter, Jonas, 0W
Hinojosa, A., 10
Ibrahim, Salah, 0F
Immonen, Marika, 05
Ishikawa, Hiroshi, 0F
Jain, Pradip Kumar, 0R
Janta-Polczynski, Alexander, 0X
Johansen, T. K., 0E
Jose, Gin, 03
Kalavrouziotis, D., 0N, 10, 17
Kanakis, I., 0E
Ketzaki, D., 10
Kumi-Barimah, Eric, 03
Kurita, Yoichiro, 16
Lakhtakia, Akhlesh, 0R
Lamprecht, T., 0E
Langlois, Richard, 0X
Lazarou, I., 0E
Leijtens, X. J. M., 11
Lemaître, F., 11
Lewoczko-Adamczyk, Wojciech, 0W
London, Yanir, 07
Lorenz, Lukas, 0O
Ma, Lin, 02, 05
Maheiros-Silveira, Gilliard N., 1A
Mangal, Nivesh, 0D
Mardoyan, H., 0E
Markey, Laurent, 14
Marx, Sebastian, 0W
Mehrpoor, G., 10
Meng, Xiang, 07
Mentovich, E., 10
Missinne, Jeroen, 0D
Mital, Rohan, 0H
Muranaka, Yusuke, 0F
Nakahara, Tatsushi, 0F
Nieweglowski, Krzysztof, 0O
O'Faolain, L., 0I
Ohira, Kazuya, 16
Orenstein, M., 10
Ott, Lennard, 0O
Pan, David Z., 0H
Pan, Zeyu, 0T
Papadovasilakis, M., 10
Patel, Jigesh, 07
Penty, Richard V., 03, 04
Pita, Julian L., 12
Pitwon, R., 0I
Porcel, M. A. G., 10
Poulopoulos, G., 0N, 17
Preve, Giovan Battista, 15
Psaila, Nicholas, 0U, 17
Reitberger, Thomas, 0O
Reithmaier, J. P., 10
Rizzo, Anthony, 07

Roccatto, D., 0E
Rouvalis, E., 0E
Rubio-Noriega, Ruth E., 1A
Rustichelli, V., 11
Sacchetto, D., 10
Sakamaki, Yohei, 0F
Santos, R., 0E
Schneider-Ramelow, Martin, 0W
Schröder, Henning, 0W
Shi, F., 04
Shi, Xinhong, 05
Shibata, Hideki, 16
Sichkovskyi, V., 10
Sirbu, Bogdan, 14
Snyder, Bradley, 0D
Spyropoulou, M., 0E
Sugizaki, Yoshiaki, 16
Taira, Yoichi, 0X
Tekin, Tolga, 14
Tessema, N. M., 0E
Torfs, G., 0E
Trajkovic, M., 11
Uemura, Hiroshi, 16
Van Campenhout, Joris, 0D
Van Steenberge, Geert, 0D
Velthaus, K.-O., 0E
Vickers, G., 0E
Vysokinos, K., 10
Warabi, Kaori, 16
Weeber, Jean-Claude, 14
White, Ian H., 03, 04
Williams, K. A., 11
Wohlfel, B., 10
Xu, Xiao, 02
Xu, Xiaochuan, 0T
Yan, Hai, 0T
Yang, Xiaoyu, 05
Ying, Zhoufeng, 0H
Zamora, Vanessa, 0W
Zervas, M., 10
Zervos, C., 0E
Zhao, Zheng, 0H
Zhu, Longxiu, 05
Ziarko, Marcin, 03

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- 4 Optical Interconnect Systems I
Richard C.A. Pitwon, University of St. Andrews (United Kingdom)
- 5 Novel Optical Waveguide and Interconnect Technologies
Ruth Houbertz, Multiphoton Optics GmbH (Germany)
- 6 Nanophotonics for Optical Interconnects
Christopher T. Middlebrook, Michigan Technological University (United States)
- 7 Fiber Optics and Micro-Optics Integration
Chris Q. Wu, Corning Incorporated (United States)
- 8 PICs for Optical Interconnects
Ray T. Chen, The University of Texas at Austin (United States)
- 9 Hybrid Device Integration Approaches for Silicon Photonic Chips
Dave J. Thomson, Optoelectronics Research Centre, University of Southampton (United Kingdom)